

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| 1 | 43 | (trenches and etch\$3 and (silicon-on-insulator)).clm. | USPAT; US-PGPUB | 2003/08/29 11:22 |
| - | 565 | (216/2).CCLS. | USPAT; US-PGPUB | 2003/05/09 16:46 |
| - | 178 | electrostatic same comb adj drive | USPAT; US-PGPUB | 2002/10/24 15:45 |
| - | 470 | etch adj stop adj material | USPAT; US-PGPUB | 2002/10/24 15:54 |
| - | 107 | (trenches and (etch-stop or etch adj stop)).clm. | USPAT; US-PGPUB | 2003/08/29 11:21 |
| - | 179 | release adj etch\$3 | USPAT; US-PGPUB | 2002/10/28 14:41 |
| - | 55 | (release adj etch\$3)and (trench or trenches) | USPAT; US-PGPUB | 2002/10/28 11:45 |
| - | 544 | release near2 etch\$3 | USPAT; US-PGPUB | 2002/10/28 11:17 |
| - | 48 | (release adj etch\$3)and (trench or trenches)and (mask or masking) | USPAT; US-PGPUB | 2002/10/28 11:45 |
| - | 247 | (216/11).CCLS. | USPAT; US-PGPUB | 2002/10/28 12:09 |
| - | 865 | (438/424).CCLS. | USPAT; US-PGPUB | 2002/10/28 12:10 |
| - | 131 | (438/412).CCLS. | USPAT; US-PGPUB | 2002/10/28 12:10 |
| - | 181 | (438/739).CCLS. | USPAT; US-PGPUB | 2002/10/28 12:10 |
| - | 192 | (438/740).CCLS. | USPAT; US-PGPUB | 2002/10/28 12:11 |
| - | 58 | release same etch\$3 same mask\$3 same trench | USPAT; US-PGPUB | 2002/10/28 14:44 |
| - | 563 | release same etch\$3 same mask\$3 | USPAT; US-PGPUB | 2002/10/28 14:44 |
| - | 311 | (MEMS or "MEM's") and (etch\$3 or releas\$) and (void or cavity) and (bond\$3 near3 wafer) | USPAT; US-PGPUB | 2003/05/09 15:51 |
| - | 50 | ("4861420" "4882933" "4904978" "4993143" "5060526" "5062302" "5084408" "5198390" "5231301" "5313836" "5326726" "5343064" "5355712" "5445988" "5447067" "5461922" "5476819" "5495761" "5503285" "5504026" "5506175" "5511428" "5537872" "5569852" "5574222" "5576250" "5578755" "5592015" "5602052" "5616523" "5627317" "5627318" "5631422" "5706565" "5719069" "5719073" "5723353" "5747353" "5747867" "5756901" "5798283" "5847280" "5847454" "5850042" "5882532" "5949144" "5959208" "6121552" "6013933" "6239473").PN. | USPAT | 2003/05/09 16:09 |
| - | 411 | (MEMS or microstructure\$1 or microelectromechanical) and (wafer adj bonding) | USPAT; US-PGPUB | 2003/08/28 17:02 |
| - | 50 | 216/2 and etch-stop | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/28 16:33 |
| - | 125 | 216/2 and accelerometer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/28 16:35 |
| - | 27 | 216/2 and accelerometer and trench | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/28 17:05 |

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|---|------|--|---|------------------|
| - | 16 | 216/2 and (filling and trenches).clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/08/28 16:55 |
| - | 1360 | (MEMS or microstructure\$1 or microelectromechanical) and trenc\$2 | USPAT; US-PGPUB | 2003/08/28 17:02 |
| - | 76 | (MEMS or microstructure\$1 or microelectromechanical) and trenc\$2 and etch-stop | USPAT; US-PGPUB | 2003/08/28 17:03 |
| - | 311 | 216/2 and trench\$2 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/08/28 17:06 |
| - | 183 | 216/2 and trench\$2 and fill\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/08/28 17:07 |